



Docket No. 56843 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Ke et al.

U.S. SERIAL NO.: 10/039,219

GROUP: 2814

FILED: January 2, 2002

EXAMINER: D. Nguyen

FOR: FLASH-PREVENTING SEMICONDUCTOR PACKAGE

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date October 24, 2003 in an envelope as "Express Mail Post Office to Addressee," mailing Label Number EV342589189US addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

By:

Michelle P. Chicos

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Commissioner for Patents
P.O. Box 1450
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Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated June 24, 2003 of the above-referenced application. A Request for Continued Examination (RCE) and a one-month extension of time are submitted herewith. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the drawings begin on page 5 of this paper.

Remarks begin on page 6 of this paper.

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Amendments to the drawings:

The attached sheet of drawings includes changes to FIG. 2. Specifically, reference numeral 18 has been added to FIG. 2, indicating a gap between the die pad 11 and the plurality of leads 12 (see specification at page 5, last paragraph). No new matter is added.

Attachment: Replacement Sheet